

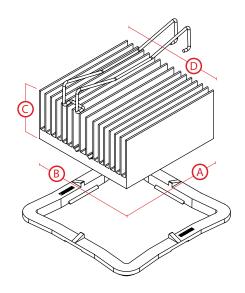
# High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

## ATS PART # ATS-53170D-C2-R0

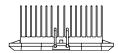
### **Features & Benefits**

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Designed specifically for BGAs and other surface mount packages
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material

**Thermal Performance** 







\*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	24.3	12.3	
300	1.5	19.1		
400	2.0	16.4		
500	2.5	14.6		
600	3.0	13.4		
700	3.5	12.4		
800	4.0	11.6		

### **Product Details**

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
17 mm	17 mm	9.5 mm	17 mm	SAINT-GOBAIN C1100F	BLACK-ANODIZED

#### NOTES

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- ATS-53170D-C1-R0 is a substitute item available utilizing an equivalent phase change material (Chomerics T766).
- 3) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170
- 6) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).